

**HAI LECK HOLDINGS LIMITED**  
(Incorporated in the Republic of Singapore)  
(Company Registration Number: 199804461D)

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**PROPOSED BONUS ISSUE – LISTING AND QUOTATION OF BONUS SHARES**

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The board of directors (the “**Board**”) of Hai Leck Holdings Limited (the “**Company**”) refers to the Company’s announcements on 14 May 2021, 31 May 2021, and 7 June 2021 in relation to the Proposed Bonus Issue (the “**Announcements**”). Unless otherwise defined herein or the context otherwise requires, all capitalised terms used in this announcement shall bear the meanings ascribed to them in the Announcements.

Further to the Announcements, the Board is pleased to inform that 20,599,248 Bonus Shares have been allotted and issued on 22 June 2021. Following the allotment and issue of the Bonus Shares, the total number of issued Shares of the Company has increased from 205,993,947 to 226,593,195 Shares.

The Bonus Shares are expected to be listed and quoted on the SGX-ST with effect from 9.00 a.m. on 24 June 2021.

BY ORDER OF THE BOARD

Cheng Buck Poh  
Executive Chairman and Chief Executive Officer

22 June 2021